Panasonic CONNECT



Windows 11 Pro Fully Rugged Laptop with 14.0" Outdoor Display and Modular Expansion Areas...

TOUGHBOOK 40 mk2

The 14.0" fully-rugged Panasonic TOUGHBOOK 40 laptop breaks new ground offering unrivaled flexibility in even the most demanding and unpredictable environments, including Defence, Mining and Utilities. It has a modular design that allows mobile workers to modify the device quickly and easily for different challenges by equipping 8 expansion areas. The powerful rugged laptop is built for use in the most extreme conditions and designed for field specialists, incorporating quick release self-encrypting secure drives and providing up to 36-hours of battery life to support mission critical operations.

Key Features

The 14" fully-rugged Panasonic TOUGHBOOK® 40 offers unrivaled flexibility in even the most demanding and unpredictable environments with its class-leading eight modular areas including its innovative modular expansion packs (xPAK's). Optical drives, authe

Windows 11 Pro

Intel® Core[™] Ultra5 135H Processor (with Intel vPro® Technology) / Intel® Core[™] Ultra7 165H (with Intel vPro® Technology) Processor optional

Up to 180cm drop resistance***, IP66 water and dust resistance, MIL-STD 810H certified***

Long battery life of up to 18 hours (up to 36 hours with optional 2nd battery*)



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https://ap.connect.panasonic.com/p h/en/toughbook-40-mk2







Model	TOUGHBOOK 40mk2, 16GB RAM,512GB SSD, 1 x standard battery pack
OS (Operating System)	Windows 11 Pro
CPU (Mobile Computing Platform) -> Processor	Intel® Core™ Ultra5 vPro™ Processor (optional Intel® Core™ Ultra7 vPro™*)
CPU (Mobile Computing Platform) -> Graphics chips	Intel® Graphics, supports Intel® ArcTM Graphics when 2 RAM Modules installed
Memory (RAM) (RAM Standard / Maximum) (Main memory)	Built-in 16GB RAM (max 64GB RAM*)
Storage	Quick release 512GB NVMe OPAL SSD (with heater)
Display & Graphics	14.0" Active Matrix (TFT) colour LCD 1920 x 1080 (FHD) LCD with sunlight-viewable glove-
	enabled touchscreen (up to 1,200cd/m ² brightness)
Wireless	Mobile Broadband:4G LTE,
	GPS:U-Blox NEO-M9N,
	Wi-Fi:Intel® Wi-Fi7 BE200,
	Bluetooth:5.1 Class 1
I/O Ports (Interface)	USB 3.2:x2 (Gen 1 Type-A),
	Micro SDXC Memory Card:x1,
	Thunderbolt 4:x1HDMI:x1,
	LAN:IEEE 802.3 10Base-T / IEEE 802.3u 100BASE-TX / IEEE 802.3ab 1000BASE-T (optional
	2nd GLAN*),
	Quad Path Through Connector:x1
Left expansion area	2nd SSD,
	Smart Card Reader, DVD Multi Drive,
Pight expansion area	Blu Ray Drive, 2nd Batterv.
Right expansion area	Smart Card Reader
Palmrest expansion area	Fingerprint reader (Windows Hello, Multi-user authentication)Contactless Smart Card
r ainn est expansion ar ea	Reader
Rear expansion area	VGA + True Serial (RS232) + 2nd native GLAN,
	USB 3.1 Type A + True Serial (RS232) + 2nd HDMI,
	USB 3.1 Type A + USB Type-C + 2nd HDMI
Camera -> Front	5MP with IR / privacy shutter (Windows Hello compliant) optional*
Audio (Sound)	Waves MaxxAudio® Stereo Speakers,
	4 integrated microphones,
	Headset:x1
Security	TPM 2.0,
	Password security,
	Integrated hardware security lock slot
Dimensions -> Main Unit	354mm x 301mm x 54.4mm (without protruding parts)
Weight -> Main Unit	Approx 3.37kg (depending on configuration)
Battery -> Battery Life	Standard: approx 12 hours (Mobile Mark [™] 25)With optional 2nd battery: approx 24 hours (Mobile Mark [™] 25)*
Power (Power supply) -> AC adapter	Input: 100V - 240V AC, 50Hz/ 60Hz, Output: 15.6V DC, 7.05A, DC In:x1
Power (Power supply) -> Battery	Lithium-Ion 10.8V, 6500mAh (typical),
(Battery pack)	6300mAh (minimum)
Power (Power supply) -> Hot Swap	Standby function, ACPI BIOS
Durability -> Drop resistance	MIL-STD810H, 180cm***
Durability -> Dust resistance	ІРбх
Durability -> Water resistance	IPx6
Operating temperature	MIL-STD810H, -29°C to +63°C***
Included in Box	Power Supply, Power Cord, Capacitive Stylus Pen, Display Cleaning Cloth and User Manual
Integrated Options	Port Replicator:x1,
Footnote Description	*Optional**One option exclusive possible in configuration port / business expansion
	module***Tested by an independent third party lab following MIL-STD810H Method 516.8 Procedure IV for transit drop test and Method 501.7 and 502.7 Procedure � for

516.8 Procedure IV for transit drop test and Method 501.7 and 502.7 Procedure operation temperature test. May differ depending on models and options